

**ABSTRACT OF THE DISCLOSURE**

It is an object to provide a plating apparatus capable of forming a plated film having a uniform thickness in a substrate to be treated. In a plating apparatus using a face down method in which a voltage is applied between a cathode electrode (5) provided in contact with a peripheral edge portion of a substrate (1) to be treated and an anode electrode (6) provided in a plating solution vessel (3), thereby carrying out plating, there is provided an anode electrode moving device (13) for vertically moving the anode electrode (6) corresponding to a plating situation of the substrate (1).